



Material Content Data Sheet



Sales Product Name	SAK-XC2765X-104F80L AA			Issued		29. August 2013		
MA#	MA001021908							
Package	PG-LQFP-100-8			Weight*		755.66 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	38.601	5.11	5.11	51082	51082
leadframe	inorganic material	phosphorus	7723-14-0	0.069	0.01		91	
	non noble metal	zinc	7440-66-6	0.275	0.04		364	
	non noble metal	iron	7439-89-6	5.501	0.73		7279	
	non noble metal	copper	7440-50-8	223.351	29.56	30.34	295569	303303
wire	noble metal	gold	7440-57-5	2.766	0.37	0.37	3660	3660
encapsulation	organic material	carbon black	1333-86-4	2.316	0.31		3065	
	plastics	epoxy resin	-	62.527	8.27		82744	
	inorganic material	silicondioxide	60676-86-0	398.319	52.69	61.27	527113	612922
leadfinish	non noble metal	tin	7440-31-5	9.288	1.23	1.23	12292	12292
plating	noble metal	silver	7440-22-4	2.495	0.33	0.33	3302	3302
glue	plastics	epoxy resin	-	2.539	0.34		3360	
	noble metal	silver	7440-22-4	7.616	1.01	1.35	10079	13439
*deviation	< 10%	Sum in total:			100,00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com